

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Heng Keong YIP</td> <td>03/12/2007</td> </tr> <tr> <td>Thoon Khin CHANG</td> <td>03/18/2007</td> </tr> <tr> <td>Chee Seng FOONG</td> <td>03/12/2007</td> </tr> </tbody> </table>		Name	Execution Date	Heng Keong YIP	03/12/2007	Thoon Khin CHANG	03/18/2007	Chee Seng FOONG	03/12/2007
Name	Execution Date								
Heng Keong YIP	03/12/2007								
Thoon Khin CHANG	03/18/2007								
Chee Seng FOONG	03/12/2007								
RECEIVING PARTY DATA									
Name:	Freescall Semiconductor, Inc.								
Street Address:	6501 William Cannon Drive West								
Internal Address:	Law Department								
City:	Austin								
State/Country:	TEXAS								
Postal Code:	78735								
PROPERTY NUMBERS Total: 1									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11738514</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11738514				
Property Type	Number								
Application Number:	11738514								
CORRESPONDENCE DATA									
Fax Number:	(512)996-6854								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	512-996-6839								
Email:	pat.thomas@freescall.com								
Correspondent Name:	Freescall Semiconductor, Inc.								
Address Line 1:	7700 West Parmer Lane								
Address Line 2:	MD: TX32/PL02								
Address Line 4:	Austin, TEXAS 78729								
ATTORNEY DOCKET NUMBER:	MT1000AK								
NAME OF SUBMITTER:	Jeslyn Goh								

CH \$40.00 11738514

Total Attachments: 3

source=MT10000AK-US-Assignment-04232007#page1.tif

source=MT10000AK-US-Assignment-04232007#page2.tif

source=MT10000AK-US-Assignment-04232007#page3.tif

PATENT ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we, **Heng Keong YIP, Thoon Khin CHANG and Chee Seng FOONG all of MALAYSIA**, have sold, assigned and transferred, and do hereby sell, assign and transfer, unto FREESCALE SEMICONDUCTOR, INC., a corporation of the State of Delaware, having its principal office in Austin, State of Texas, United States of America, and its successors, assigns, and legal representatives, the entire right, title and interest for the United States of America in and to certain inventions relating to improvements in, **METHOD OF MAKING SOLDER PAD** (Docket No. **MT10000AK**), described, illustrated and claimed in an application for Letters Patent of the United States of America executed by me on the dates indicated by my signature below, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation or reissue thereof.

We hereby also sell, assign and transfer unto FREESCALE SEMICONDUCTOR, INC., the entire right, title and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the invention and the applications for Letters Patent in foreign countries, and I further authorize FREESCALE SEMICONDUCTOR, INC. to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

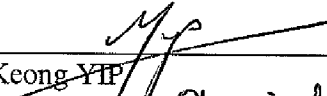
We hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation or reissue, to FREESCALE SEMICONDUCTOR, INC., for the sole use and benefit of FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives, to the full end of the term for which Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and I hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to FREESCALE SEMICONDUCTOR, INC.

We agree that, when requested, we will, without charge to FREESCALE SEMICONDUCTOR, INC., but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives or nominees.

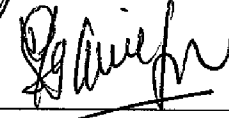
MT10000AK

1

We covenant with FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.


Heng Keong YIP

DATE: 12-MAR-07


WITNESS

DATE: 12. MAR. 07

mf.
WITNESS

DATE: 12 MARCH 07

Thoon Khin CHANG

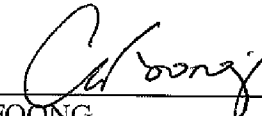
DATE: _____

WITNESS

DATE: _____

WITNESS

DATE: _____


Chee Seng FOONG

DATE: Mar 12 2007


WITNESS

DATE: 12. MAR. 07

mf.
WITNESS

DATE: 12 MARCH 07.